

## ERSA Bar Solder

ERSA bar solder, like solder wire, is recovered from initial melt solder. It is primarily used for filling solder baths. For easier melting, it can be supplied as required in 50 mm sections. In combination with soldering irons of greater power and with suitable flux, bar solder is also used for soldering cable lugs of larger cross-sections and in sheet metal work.



### Bar solder

High-quality bar solder recovered from initial melt solder to refill solder baths.

Order no.	Alloy	Melting temperature	Delivered in
4LOT230GAG3.5CU0.7	Sn95.5Ag3.5Cu0.7	217 - 218 °C	Bars of approx. 230 g
4LOT230G64B	Sn64Pb36	183 °C	Bars of approx. 230 g

## ERSA Solder Wire

ERSA solder wire consists exclusively of high-quality raw materials. Manufactured on state-of-the-art machines, the wire meets all quality requirements.

It is manufactured in different dimensions and with different alloys, to meet all practical requirements.

Different types of "flux cores" allow individual adaptation to all soldering needs, especially in electronics and the electronics industry.



### Solder wire

Available in different alloys and drum sizes in order to meet various fields of application. Please refer to the ERSA price list or to [www.ersa.com](http://www.ersa.com) for a detailed list including wire diameters.



ATTENTION: According to the EU Directive as of July 1, 2006 lead may no longer be used in electronic assemblies.

Solder alloy according to DIN EN 29453	Flux according to DIN EN ... ... % flux share	Melting temperature (°C)
Sn96.5Ag3.0Cu0.5	29454 art. 1, type 1.1.3.B, or DIN EN 61190-1-3, ROL 0.3.5 %, halogen-free	217
Sn96.5Ag3.0Cu0.5	29454, type 1.2.3., J-STD-004 RE/LO 1.6 %, halogen-free	217 - 219
Sn96.5Ag3.0Cu0.5	29454, type 1.2.3., J-STD-004 RE/LO 2.2 %, halogen-free	217 - 219
Sn99.3CuNiGe0.7 (based on Sn99.3Cu0.7)	29454 art. 1, type 1.1.3.B, or DIN EN 61190-1-3, ROL 0.3.5 %, halogen-free	227
Sn99.3Cu0.7	29454, type 1.2.3., J-STD-004 RE/LO, 1.6 %, halogen-free	227
Sn96.5Ag3.5	29454 art. 1, type 1.1.3.B, or DIN EN 61190-1-3, ROL 0.3.5 %, halogen-free	221
Sn96.5Ag3.5	29454, type 1.2.3., J-STD-004 RE/LO, 1.6 %, halogen-free	221
Low-residue, halogen-free No-Clean solder wire. Especially adapted to the requirements in electronics production. The flux stands out by high temperature resistance, and it does not spray while melting. The light, solid flux residues are neither corrosive nor electrically conductive. Consequently it is not necessary to remove them from the solder joint.		
Sn60Pb40	29454/1.1.2, 2.2 %	183 - 190
Sn60Pb40	29454/1.2.3, 1.4 %	183 - 190
Sn60Pb39Cu1	29454/1.1.2, 2.2 %	183 - 190
Sn63Pb37	29454/1.1.3, 2.2 %, halogen-free, eutectic	183
Sn63Pb37	29454, type 1.2.3, J-STD-004 RE/LO, 0.9 %, halogen-free	183
Sn63Pb37	29454, type 1.2.3, J-STD-004 RE/LO, 0.6 %, halogen-free	183
Sn62Pb36Ag2	29454, type 1.2.3, J-STD-004 RE/LO, 0.6 %, halogen-free	178 - 188

subject to changes